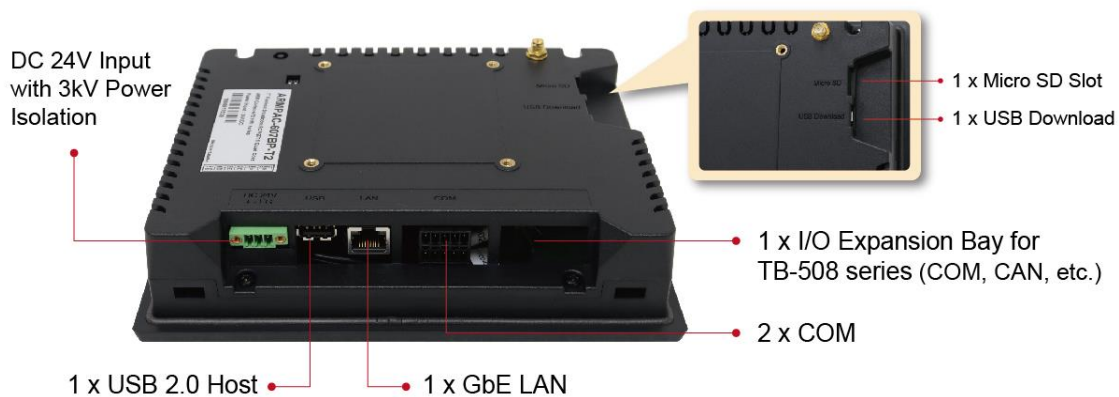


ARMPAC-6B I/O connectivity and expansibility

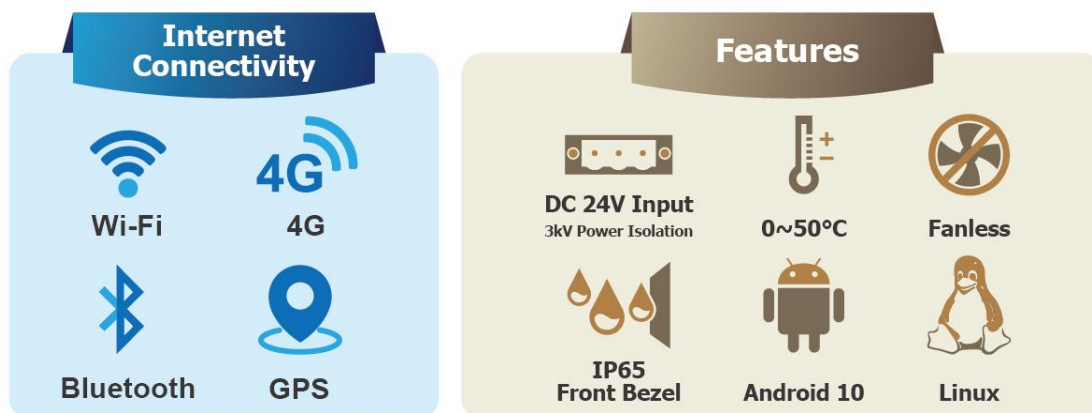
ARMPAC-6B features IP65 compliant front flat bezel with plastic chassis to provide a lightweight, durable, rugged and cost-effective factory automation solution. It comes in

1 x USB 2.0, 1 x USB download, 2 x COM and 1 x GbE LAN. As for expansion, it provides 1 x micro sim card slot, on board module for internet connectivity of 4G, Wi-Fi, Bluetooth and GPS with antenna holes; and 1 x I/O expansion bay for expansion card TB-508 series to expand I/O connectors for customers to meet their demands.



Rugged ARMPAC-6B is well prepared for industrial automation application

ARMPAC-6B comes in fan-less design but is able to operate under wide range temperature from 0 ~ 50°C. It requires ultra-low power consuming with DC 24V input with 3kV power isolation as well. Furthermore, ARMPAC-6B provides flexible software customization service with multiple operating system, such as Android 10 and Yocto Linux.



ARMPAC-6B offers high expansibility of I/O interfaces and software support. It has equipped with various advantages, including having high computing and graphic performance, lightweight but stable construction, reliable and easy to maintenance features. By all benefits ARMPAC-6B brings, it can highly integrate with peripheral devices in industrial automation applications.

Products Guide:

Model	ARMPAC-607BP	ARMPAC-610BP
Size	7" TFT-LCD	10.1" TFT-LCD
Processor	Broadcom BCM2711, ARM Cortex-A72 (4x Cores, up to 1.5GHz)	
Memory	Onboard DDR4 4GB SDRAM	
Storage	16GB / 32GB eMMC Flash	
Expansion slot	1 x Half / Full-size mPCIe slot with Micro SIM slot TB-508 series I/O Expansion Board	
OS System	Android 10 (Default) / Yocto Linux	
Certifications	Total IP66/IP69K	